

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims.

1.-36. Canceled.

37. (Currently Amended) A clad board for forming circuitry, the clad board being manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet;

resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermosetting resin having a semi-cured portion; and

a resin layer formed smoothly on the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet comprises:

a first surface and a second surface,

a first layer disposed at the first surface of the fiber sheet, and

a second layer, and

a third layer disposed at the second surface of the fiber sheet, the second layer being located between the first layer and the third layer, and

wherein the density of the second layer is lower than~~different from~~ the density of the first layer and lower than the density of the third layer.

38-39. Canceled

40. (Previously Presented) The clad board of claim 37, wherein the fiber sheet has a density ranging from 700 kg/m<sup>3</sup> to 1000 kg/m<sup>3</sup>.

41-46. Canceled

47. (Previously Presented) A clad board for forming circuitry, the clad board manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being either a non-through-hole or a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet;

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet;

resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion; and

a resin layer formed smoothly on the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet includes:

first and second layers disposed at respective surfaces of the fiber sheet; and

a third layer located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers.

48-58. Canceled

59. (Previously Presented) The clad board of claim 37,

wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste including non-spherical-shaped conductive particles.

60-65. Canceled

66. (Currently Amended) A core board for a clad board for forming circuitry, said core board comprising:

a fiber sheet;

resin material impregnated into the fiber sheet, the resin material including at least one of a thermoplastic resin and a thermosetting resin having semi-cured portion; and

a resin layer formed on the fiber sheet, the resin layer being made of material identical to the resin material;

wherein: the fiber sheet comprises:

a first surface and a second surface,

a first layer disposed at the first surface of the fiber sheet, and

a second layer, and

a third layer disposed at the second surface of the fiber sheet, the second layer being located between the first layer and the third layer; and

wherein the density of the second layer is different from lower then the density of the first layer and lower than the density of the third layer.

67-68. Canceled

69. (Previously Presented) The core board of claim 66, wherein the fiber sheet has a density ranging from  $700 \text{ kg/m}^3$  to  $1000 \text{ kg/m}^3$ .

70-75. Canceled

76. (Previously Presented) A core board for a clad board for forming circuitry, the core board comprising:

a fiber sheet;

resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion; and

a resin layer formed on the fiber sheet, the resin layer being made of material identical to the resin material;

wherein the fiber sheet includes;

first and second layers disposed at respective outermost sides of the fiber sheet; and

a third layer located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers.

77-82. Canceled

83. (Previously Presented) The clad board of claim 47, wherein the fiber sheet has a density ranging from  $700 \text{ kg/m}^3$  to  $1000 \text{ kg/m}^3$ .

84. (Previously Presented) The clad board of claim 47, wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

85. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a density ranging from 700 kg/m<sup>3</sup> to 1000 kg/m<sup>3</sup>.

86. (Previously Presented) The clad board of claim 37, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

87. (Previously Presented) The core board of claim 66, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

88. (New) The clad board of claim 37, wherein the fiber sheet is a non-woven fabric.

89. (New) The clad board of claim 88, wherein the fiber sheet is an aramid fiber non-woven fabric.

90. (New) The clad board of claim 47, wherein the fiber sheet is a non-woven fabric.

91. (New) The clad board of claim 90, wherein the fiber sheet is an aramid fiber non-woven fabric.

92. (New) The core board of claim 66, wherein the fiber sheet is a non-woven fabric.

93. (New) The core board of claim 92, wherein the fiber sheet is an aramid fiber non-woven fabric.

94. (New) The core board of claim 76, wherein the fiber sheet is a non-woven fabric.

95. (New) The clad board of claim 94, wherein the fiber sheet is an aramid fiber non-woven fabric.